

Title (en)

ELECTROPLATING BATH FOR ELECTROCHEMICAL DEPOSITION OF A CU-SN-ZN-PD ALLOY LAYER, METHOD FOR ELECTROCHEMICAL DEPOSITION OF SAID ALLOY LAYER, SUBSTRATE COMPRISING SAID ALLOY LAYER AND USES OF THE COATED SUBSTRATE

Title (de)

GALVANIKBAD ZUR ELEKTROCHEMISCHEN ABSCHEIDUNG EINER CU-SN-ZN-PD LEGIERUNGSSCHICHT, VERFAHREN ZUR ELEKTROCHEMISCHEN ABSCHEIDUNG DER LEGIERUNGSSCHICHT, SUBSTRAT MIT DER LEGIERUNGSSCHICHT UND VERWENDUNGEN DES BESCHICHTETEN SUBSTRATS

Title (fr)

BAIN GALVANIQUE POUR LE DÉPÔT ÉLECTROCHIMIQUE D'UNE COUCHE D'ALLIAGE CU-SN-ZN-PD, PROCÉDÉ DE DÉPÔT ÉLECTROCHIMIQUE DE CETTE COUCHE D'ALLIAGE, SUBSTRAT COMPRENNANT CETTE COUCHE D'ALLIAGE ET UTILISATIONS DU SUBSTRAT REVÊTU

Publication

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Application

**EP 15187511 A 20150930**

Priority

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Abstract (en)

The invention provides an electroplating bath for electrochemical deposition of a novel Cu-Sn-Zn-Pd alloy on a substrate. The novel alloy is characterized by exceptional corrosion resistance and the commonly used precious metal intermediate layer (e.g. a Pd-layer) between the substrate and the finishing layer is no longer necessary which allows a substantial reduction of the production costs of the plated substrates.

IPC 8 full level

**C22C 9/02 (2006.01)**

CPC (source: EP US)

**C22C 9/02 (2013.01 - EP); C25D 3/58 (2013.01 - EP US); C25D 3/60 (2013.01 - EP); C25D 5/10 (2013.01 - EP US); C25D 5/611 (2020.08 - EP US); C25D 5/627 (2020.08 - EP US); C25D 7/005 (2013.01 - EP)**

Citation (applicant)

- EP 1930478 B1 20130619 - ENTHONE [US]
- EP 2035602 B1 20120321 - BYD CO LTD [CN]
- EP 2757180 A1 20140723 - VALMET S P A [IT]
- CN 1175287 A 19980304 - CITIZEN WATCH CO LTD [JP]

Citation (search report)

- [X] JP 3029948 B2 20000410
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DOCDB simple family (application)

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